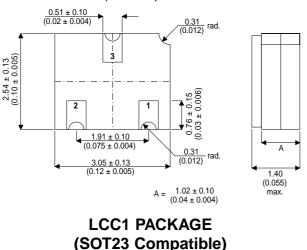
## 1N6638CSM



#### MECHANICAL DATA

Dimensions in mm(inches)



# SWITCHING DIODE IN A CERAMIC SURFACE MOUNT PACKAGE FOR HI-REL APPLICATIONS

## **FEATURES**

- HERMETIC CERAMIC SURFACE MOUNT PACKAGE
- SCREENING OPTIONS AVAILABLE

Pad 1 – Anode Pad 2 – N/C Pad 3 – Cathode

## ABSOLUTE MAXIMUM RATINGS (Tcase = 25°C unless otherwise stated)

V <sub>BR</sub>	Breakdown Voltage	150V		
V <sub>RWM</sub>	Working Peak Reverse Voltage	125V		
I <sub>F(AV)</sub>	Average Forward Current	300mA		
I <sub>FSM(surge)</sub>	Repetitive Forward Current	2.5A		
TJ	Operating Junction Temperature	-65 to +175°C		
T <sub>STG</sub>	Storage Junction Temperature	-65 to +175°C		
R <sub>θJC</sub>	Thermal Resistance Junction To Case	20°C/W		

### ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25°C unless otherwise stated)

Parameter		Test Conditions	Min.	Тур.	Max.	Unit
V <sub>F1</sub>	Forward Voltage	I <sub>F</sub> = 10mA (Pulsed)		0.8		V
I <sub>R1</sub>	Leakage Current	V <sub>R</sub> = 20V		35		nA
I <sub>R2</sub>	Leakage Current	$V_{R} = V_{RWM}$		0.5		μA
t <sub>fr</sub>	Forward Recovery Time	I <sub>F</sub> = 50mA		20		ns
t <sub>rr</sub>	Reverse Recovery Time	$I_{RM} = I_F = 10 \text{mA}$		4.5		ns
C <sub>T1</sub>	Total Capacitance	$V_{R} = 0V$		2.5		pF

Semelab PIc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.